

Microsemi Corporation

November 16, 2016

Product/Process Change Notification No: 156662

Change Classification: Major

Subject: Assembly Qualification of UTAC Thailand for PoE Products in QFN packages

Description of Change:

Microsemi is qualifying an alternative assembly site for the PoE product family at UTAC, Thailand (UTL). UTL is currently a qualified assembly site for Microsemi.

The BOM changes are listed in the table below.

| | Current BOM | UTL BOM |
|----------------------|------------------|------------------|
| Mold Compound | G770HCD | G700LTD |
| Die Attach | 2700HT or QMI519 | 590-4HT1 or 8600 |
| Wire | PdCu or Au | AuPdCu |
| Lead Finish | PPF or Matte-Tn | PPF or Matte-Tn |

The Moisture Sensitivity Level (MSL) requirement for the products in this package will also be changing from MSL1 to MSL3. Packaging for the associated part numbers will change to dry pack with desiccant, and slightly larger boxes will be used to accommodate this new packing material.

Reason for Change:

The location change is to align with a Corporate Operations subcontractor consolidation initiative. Changing to MSL3 will increase package robustness in reflow and standardizes the products across packages.

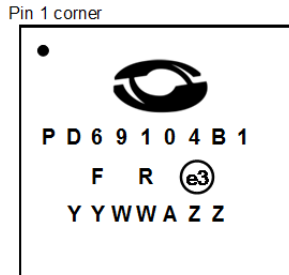
Application Impact:

There is no impact to the customers' applications since there are no changes to form, fit, function, or product reliability as a result of the move. Receiving departments should be informed that the new boxes may have a slight difference in dimensions, and the material will require MSL3 handling. Datasheets will be updated accordingly.

Method of Identifying Changed Product:

The assembly location is listed on the product package box and tape and reel labels.

Product assembled at the new assembly location will have a new standardized marking format which includes assembly site and production revision identifiers. These identifiers will be in the second line of text in the new marking. See an example below:



Products Affected by this Change:

| Package | Body Size | Pin Count | Ordering Part number |
|---------|-----------|-----------|----------------------|
| DFN | 4x3 | 12 | PD70100ILD-TR |
| DFN | 4x3 | 12 | PD70200ILD-TR |
| QFN | 4x5 | 24 | PD69101ILQ-13155-TR |
| QFN | 4x5 | 24 | PD69101ILQ-TR |
| DFN | 4x5 | 16 | PD70210AILD-TR |
| DFN | 4x5 | 16 | PD70210ILD-TR |
| QFN | 4x5 | 24 | PD81001ILQ-TR |
| QFN | 5x7 | 38 | PD70210ALILQ-TR |
| QFN | 6x8 | 40 | PD70224ILQ-TR |
| QFN | 7.5x10 | 52 | PD70224LILQ-TR |
| QFN | 8x8 | 48 | PD69104ILQ-TR |
| QFN | 8x8 | 48 | PD69104B1ILQ-TR |
| QFN | 8x8 | 48 | PD69104B1FILQ-TR |
| QFN | 8x8 | 48 | PD69104B2ILQ-TR |
| QFN | 8x8 | 48 | PD69104FILQ-TR |
| QFN | 8x8 | 48 | PD69108ILQ-TR |
| QFN | 8x8 | 48 | PD69108FILQ-TR |

Note: This is a list of Ordering Part Numbers (OPNs) as are found in product datasheets. Customers may track additional part number variants in their systems, so please consider this a base part list.



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Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

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Production Shipment Schedule:

Product assembled at the new assembly site, with the new material BOM and in MSL3 pack is planned to ship no sooner than February 15, 2017 unless customers provide written acceptance of the new product.

During a transition period, customers may see shipments with either location while any existing inventory of parts is depleted.

Qualification Data:

Qualification Reports will be available in December 2016.

Samples Availability:

Samples are available upon request.

Please contact your local Microsemi representative to place sample orders.

Contact Information:

Communications Products Group
CMPG.quality@microsemi.com

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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CHANGE APPROVAL SUPPLEMENT

Customer Acknowledgement / Approval for Product/Process Change Notification No: 156662

Microsemi Corporation intends to implement this change 90 days after this notification. Acknowledgement of your company's acceptance of this change is requested per contractual agreement. Response within 30 days is required.

Accepted

Rejected

Signature

Date

Name

Title

Please enter rationale for rejection, if applicable: _____



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